- Purpose: To determine the viability of using TDR based measurements and software to extract SPICE models for use in running performance simulations of Gbit links.
 - Identify strengths and weaknesses of the approach
 - Determine what can be safely modeled and what must be measured
- Method:
 - Measurements of cable assemblies, test fixtures(TDR/TDT)
 - Extraction of SPICE models from measurements
 - Eye pattern measurements
 - Performance simulation using SPICE models
 - Comparison of results

- This is work in process
- Intent today is to show progress and gather input as to what other questions should be addressed through this exercise
- Joint effort of:
 - Mark Marlett Cypress Semiconductor
 - Dima Smolyansky TDA Systems
 - John Sawdy Meritec
 - Chris Shmatovich Meritec

Experiment Flowchart



Physical Components



Modeling Study Cable Assemblies

- 2meter, 5 meter lengths
- MicroGiga connectors
- 24 awg conductors
- 100 ohms



Model Interconnections



John Sawdy Meritec/Joy Signal 7/18/02

Modeling Study Spice Example

* Time Domain Analysis Systems: IConnect

- * Version 2.0.1 (Internal Release)
- * File Created: July 18, 2002 at 02:23PM
- * Created By: JSAWDY

* Format: Model

- * Type: Lossy Line
- * == Begin Header ==
- * Termination: Matched
- * Reference Waveform: ..\Meri 2 meter\2ns_div\open.wfm
- * Reflection Waveform: ..\Meri 2 meter\2ns_div\reflection.wfm
- * Transmission Waveform: ...\Meri 2 meter\2ns div\thru.wfm
- * Parameters: Rdc=650m, Rac=30.7u, Linf=451n, Gdc=256n, Gac=9.01p, Cinf=169p
- * Format: W-Element
- * Length: 1
- * Syntax: HSpice
- * Name: Automatically Generated

* == End Header ==

.subckt Lossy_Line_2_meter port1 port2 gnd_

W1 N=1 port1 gnd_ port2 gnd_ RLGCMODEL=Lossy_Line_2_meter_Model L=1

```
* RLGC values for W element
.MODEL Lossy_Line_2_meter_Model W MODELTYPE=RLGC N=1
+ Lo=4.51e-007
+ Co=1.72003e-010
+ Ro=0.65
+ Go=0
+ Rs=3.07e-005
+ Gd=1.20133e-011
```

.ends

2 Meters, 1 Gbit





2 Meters, 2 Gbit











5 Meters, 1 Gbit





5 Meter, 2 Gbit



5 Meter, 4 Gbit





Modeling Study Next Actions

- Include Silicon in measurements and models
- SPICE simulations including the active devices
- Quantify degree of correlation between measurements and simulations
- _
- _
- _
- _